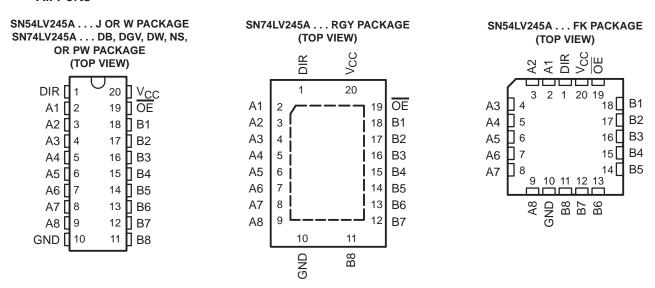
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- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 6.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



description/ordering information

These octal bus transceivers are designed for 2-V to 5.5-V V_{CC} operation.

ORDERING INFORMATION

TA	PACKA	.GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Reel of 1000	SN74LV245ARGYR	LV245A
	2010 5111	Tube of 25	SN74LV245ADW	11/0454
	SOIC - DW	Reel of 2000	SN74LV245ADWR	LV245A
	SOP – NS	Reel of 2000	SN74LV245ANSR	74LV245A
4000 1- 0500	SSOP – DB	Reel of 2000	SN74LV245ADBR	LV245A
–40°C to 85°C		Tube of 70	SN74LV245APW	
	TSSOP - PW	Reel of 2000	SN74LV245APWR	LV245A
		Reel of 250	SN74LV245APWT	
	TVSOP - DGV	Reel of 2000	SN74LV245ADGVR	LV245A
	VFBGA – GQN	Reel of 1000	SN74LV245AGQNR	LV245A
	CDIP – J	Tube of 20	SNJ54LV245AJ	SNJ54LV245AJ
-55°C to 125°C	CFP – W	Tube of 85	SNJ54LV245AW	SNJ54LV245AW
	LCCC – FK	Tube of 55	SNJ54LV245AFK	SNJ54LV245AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

The 'LV245A devices are designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so the buses are effectively isolated.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

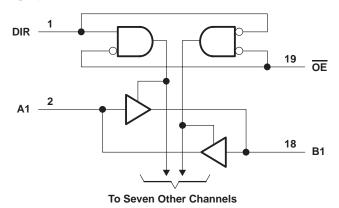
terminal assignments

	1	2	3	4
Α	A1	DIR	Vcc	OE
В	А3	B2	A2	B1
С	A5	A4	B4	В3
D	A7	B6	A6	B5
Е	GND	A8	B8	В7

FUNCTION TABLE

INP	UTS	ODED ATION					
OE	DIR	OPERATION					
L	L	B data to A bus					
L	Н	A data to B bus					
Н	X	Isolation					

logic diagram (positive logic)



Pin numbers shown are for the DB, DGV, DW, FK, J, NS, PW, RGY, and W packages.



SN54LV245A, SN74LV245A OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} Input voltage range, V _I : Except I/O ports (see Note 1)		
I/O ports (see Notes 1 and 2)		
Voltage range applied to any output in the high-impedance or		
power-off state, V _O (see Note 1)	-0.5 \	/ to 7 V
Output voltage range applied in the high or low state, V _O (see Notes 1 and 2)0.5 V to	V _{CC}	+ 0.5 V
Input clamp current, I _{IK} (V _I < 0)		
Output clamp current, I _{OK} (V _O < 0)		
Continuous output current, I_O ($V_O = 0$ to V_{CC})		
Continuous current through V _{CC} or GND		
Package thermal impedance, θ _{JA} (see Note 3): DB package		
(see Note 3): DGV package		
(see Note 3): DW package		
(see Note 3): GQN package		
(see Note 3): NS package		
(see Note 3): PW package		
(see Note 4): RGY package		
Storage temperature range, T _{stq} –65		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.
- 4. The package thermal impedance is calculated in accordance with JESD 51-5.



SN54LV245A, SN74LV245A OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 5)

			SN54L	V245A	SN74I	V245A	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
.,	10.11	V _{CC} = 2.3 V to 2.7 V	V _{CC} ×0.7		V _{CC} ×0.7		.,
V_{IH}	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	V _{CC} × 0.7		$V_{CC} \times 0.7$		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	V _{CC} × 0.7		$V_{CC} \times 0.7$		
		V _{CC} = 2 V		0.5		0.5	
.,	Landa de la Caractera de la ca	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		V _{CC} ×0.3		$V_{CC} \times 0.3$.,
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		V _{CC} ×0.3		$V_{CC} \times 0.3$	V
		V _{CC} = 4.5 V to 5.5 V		V _{CC} ×0.3		V _{CC} × 0.3	
٧ı	Input voltage		0	5.5	0	5.5	V
.,	0.1.1.11	High or low state	0	[∠] V _C C	0	Vcc	.,
VO	Output voltage	3-state	0 ,	5.5	0	5.5	V
		V _{CC} = 2 V	3	-50		-50	μΑ
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	20	-2		-2	
ЮН	High-level output current	V _{CC} = 3 V to 3.6 V	2	-8		-8	mA
		V _{CC} = 4.5 V to 5.5 V		-16		-16	
		V _{CC} = 2 V		50		50	μΑ
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2	
loL	Low-level output current	V _{CC} = 3 V to 3.6 V		8		8	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		16		16	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		200	
Δt/Δν	Input transition rise or fall rate	V _{CC} = 3 V to 3.6 V		100		100	ns/V
		V _{CC} = 4.5 V to 5.5 V		20		20	
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN54	4LV245A		SN74	LV245A		
PA	ARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
		I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			V _{CC} -0.1			
		I _{OH} = -2 mA	2.3 V	2			2			V
VOH		$I_{OH} = -8 \text{ mA}$	3 V	2.48			2.48			V
		I _{OH} = -16 mA	4.5 V	3.8			3.8			
		I _{OL} = 50 μA	2 V to 5.5 V		4	0.1			0.1	
		I _{OL} = 2 mA	2.3 V		1	0.4			0.4	v
VOL		I _{OL} = 8 mA	3 V		2/4	0.44			0.44	V
		I _{OL} = 16 mA	4.5 V		7	0.55			0.55	
Тį	Control inputs	V _I = 5.5 V or GND	0 to 5.5 V	2	5	±1			±1	μΑ
loz	A or B port	$V_O = V_{CC}$ or GND	5.5 V	0		±5			±5	μΑ
Icc	_	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	Q		20			20	μΑ
l _{off}		V_{I} or $V_{O} = 0$ to 5.5 V	0			5			5	μΑ
		V V 0V5	3.3 V		3			3		_
Ci	Control inputs	$V_I = V_{CC}$ or GND	5 V		3			3		pF
	A on D mont	V- V or CND	3.3 V		5.5			5.5		
C _{io}	A or B port	$V_O = V_{CC}$ or GND	5 V		5.5			5.5		pF

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	T,	4 = 25°C	;	SN54L	/245A	SN74LV	/245A	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t pd	A or B	B or A			8.3*	13*	1*	15*	1	15	
t _{en}	ŌE	A or B	C _L = 15 pF		11.8*	19.9*	1*	22*	1	22	ns
^t dis	ŌĒ	A or B			11.8*	18.1*	1*	20*	1	20	
^t pd	A or B	B or A			11.2	15.9	1/	18	1	18	
t _{en}	ŌĒ	A or B	0 50 5		14.1	22.7	277	26	1	26	
^t dis	ŌĒ	A or B	$C_L = 50 pF$		17.6	23.1	0 1	25	1	25	ns
t _{sk(o)}						2	Q			2	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	Δ = 25°C	;	SN54L	/245A	SN74L\	V245A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t pd	A or B	B or A			5.9*	8.4*	1*	10*	1	10	
t _{en}	ŌĒ	A or B	C _L = 15 pF		8.2*	13.2*	1*	15.5*	1	15.5	ns
^t dis	ŌĒ	A or B			9.6*	16.5*	1*	19.5*	1	19.5	
^t pd	A or B	B or A			7.9	11.9	1	13.5	1	13.5	
t _{en}	ŌĒ	A or B	0 50 5		9.9	16.7	77	19	1	19	
^t dis	ŌĒ	A or B	C _L = 50 pF		13.9	19.8	Q 1	22	1	22	ns
tsk(o)						1.5	Q"			1.5	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T _A = 25°C		SN54L	V245A	SN74L\	/245A		
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t pd	A or B	B or A			4.3*	5.5*	1*	6.5*	1	6.5	
t _{en}	ŌĒ	A or B	C _L = 15 pF		5.7*	8.5*	1*	10.6*	1	10	ns
^t dis	ŌĒ	A or B			7.8*	12.8*	1*	14.7*	1	14.2	
^t pd	A or B	B or A			5.6	7.5	1	8.5	1	8.5	
t _{en}	ŌĒ	A or B	0 50 5		7	10.6	3	12	1	12	
t _{dis}	ŌĒ	A or B	$C_L = 50 pF$		10.9	14.7	Q 1	16	1	16	ns
tsk(o)						1	Q'			1	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 6)

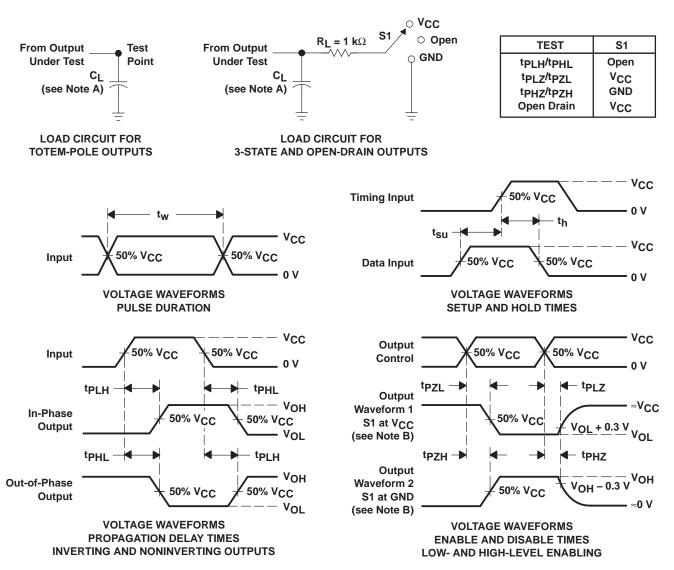
	DADAMETED	SN	SN74LV245A			
	PARAMETER	MIN	TYP	MAX	UNIT	
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.5	0.8	V	
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.4	-0.8	V	
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		2.9		V	
V _{IH(D)}	High-level dynamic input voltage	2.31			V	
V _{IL(D)}	Low-level dynamic input voltage			0.99	V	

NOTE 6: Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

PARAMETER			TEST CO	VCC	TYP	UNIT	
<u> </u>	Davis discination consistence	Outrote analysed	C. 50 F	f 40 MH-	3.3 V	20	٠.
Cpd	Power dissipation capacitance	Outputs enabled	$C_L = 50 pF$,	f = 10 MHz	5 V	25	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpZL and tpZH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







25-Oct-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV245ADBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74LV245ADBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245ADBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245ADGVR	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245ADGVRE4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245AGQNR	ACTIVE	VFBGA	GQN	20	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74LV245ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245APWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245APWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74LV245APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245APWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245APWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245APWT	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245APWTE4	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV245ARGYR	ACTIVE	QFN	RGY	20	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LV245ARGYRG4	ACTIVE	QFN	RGY	20	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LV245AZQNR	ACTIVE	VFBGA	ZQN	20	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.



PACKAGE OPTION ADDENDUM

25-Oct-2005

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

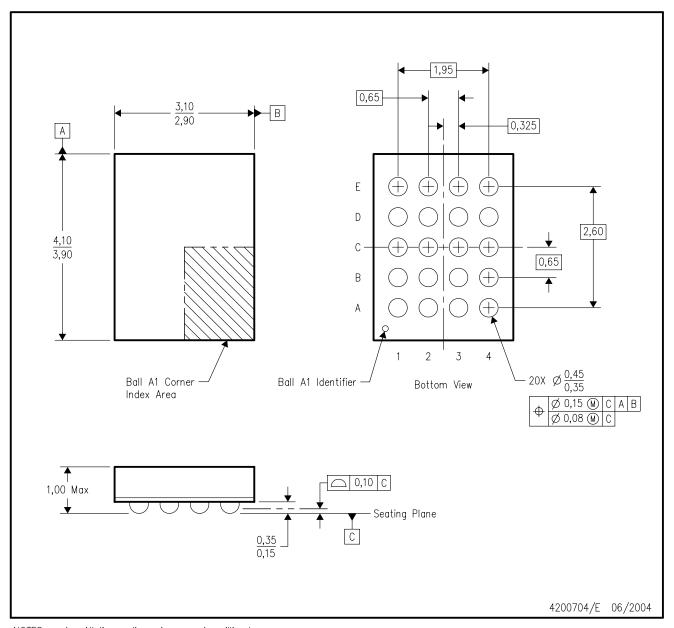
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



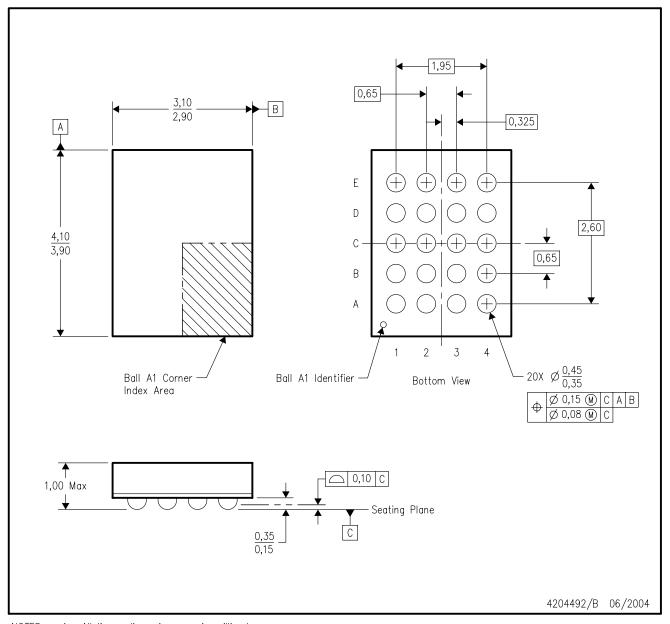
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BC.
- D. This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.



ZQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BC.
- D. This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead (SnPb).



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



DW (R-PDSO-G20)

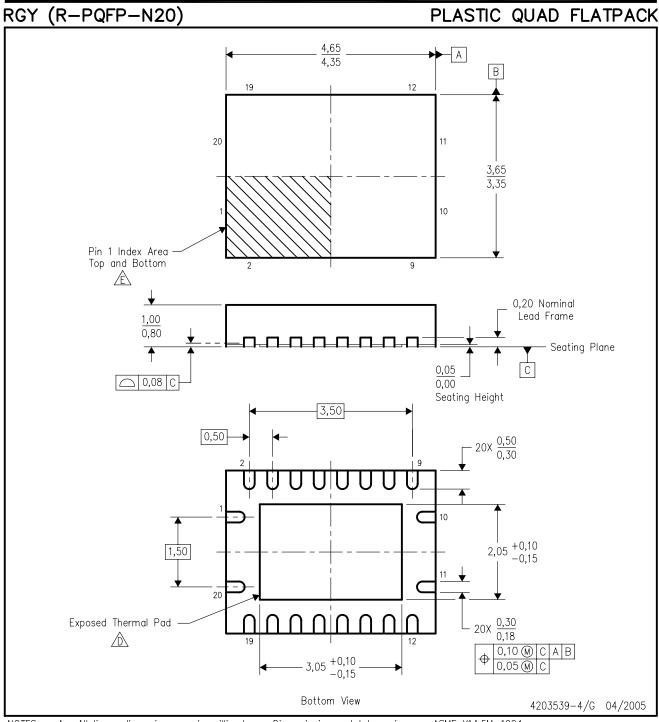
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.





NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal pad must be soldered to the board for thermal and mechanical performance.
- Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- F. Package complies to JEDEC MO-241 variation BC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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